

Amendments to the Drawings:

The attached sheets of drawings include changes to Fig. 1, Fig. 4, and Fig. 5. In Fig. 1, the gaps between the tie-bars and the die pad have been deleted; in Fig. 4, the characters 5 have been changed to characters B and the gaps between the tie-bars and the die pad have been deleted; and in Fig. 5, the character 102 has been changed to 100, and the pins have been deleted.

Attachments: Replacement Sheets

Annotated Sheet Showing Changes.

Remarks

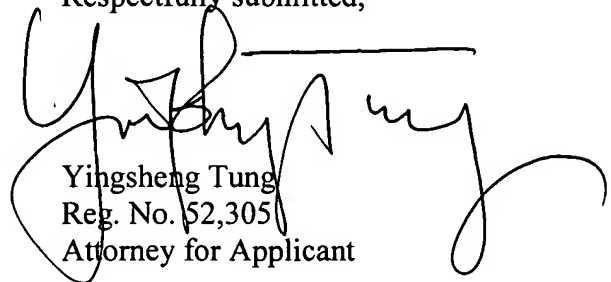
Following the Restriction Requirement of October 3, 2005, applicant elects claims 1-6, 10, and 11, with amendments to claims 1, 4, 10, and 11; cancels claims 7, 8, 9, and 12-21; and inserts new claims 22-25 for examination. The amendments make the claims describing the invention more clear without adding new matter. The newly inserted claims 22-25 are fully supported in the original specification and in the original drawings.

In the amended Fig. 1, the gaps between the tie-bars and the die pad have been deleted. In the amended Fig. 4, the same gaps have been deleted and the characters 5 have been changed to characters B. In the amended Fig. 5, the character 102 has been changed to character 100, and the leads 32A and 30A have been deleted.

In view of the examiner's restriction requirement, applicant retains the right to present claims 15-22 in a divisional application.

Applicant respectfully requests that a timely examination of this application and the allowance of all pending claims.

Respectfully submitted,



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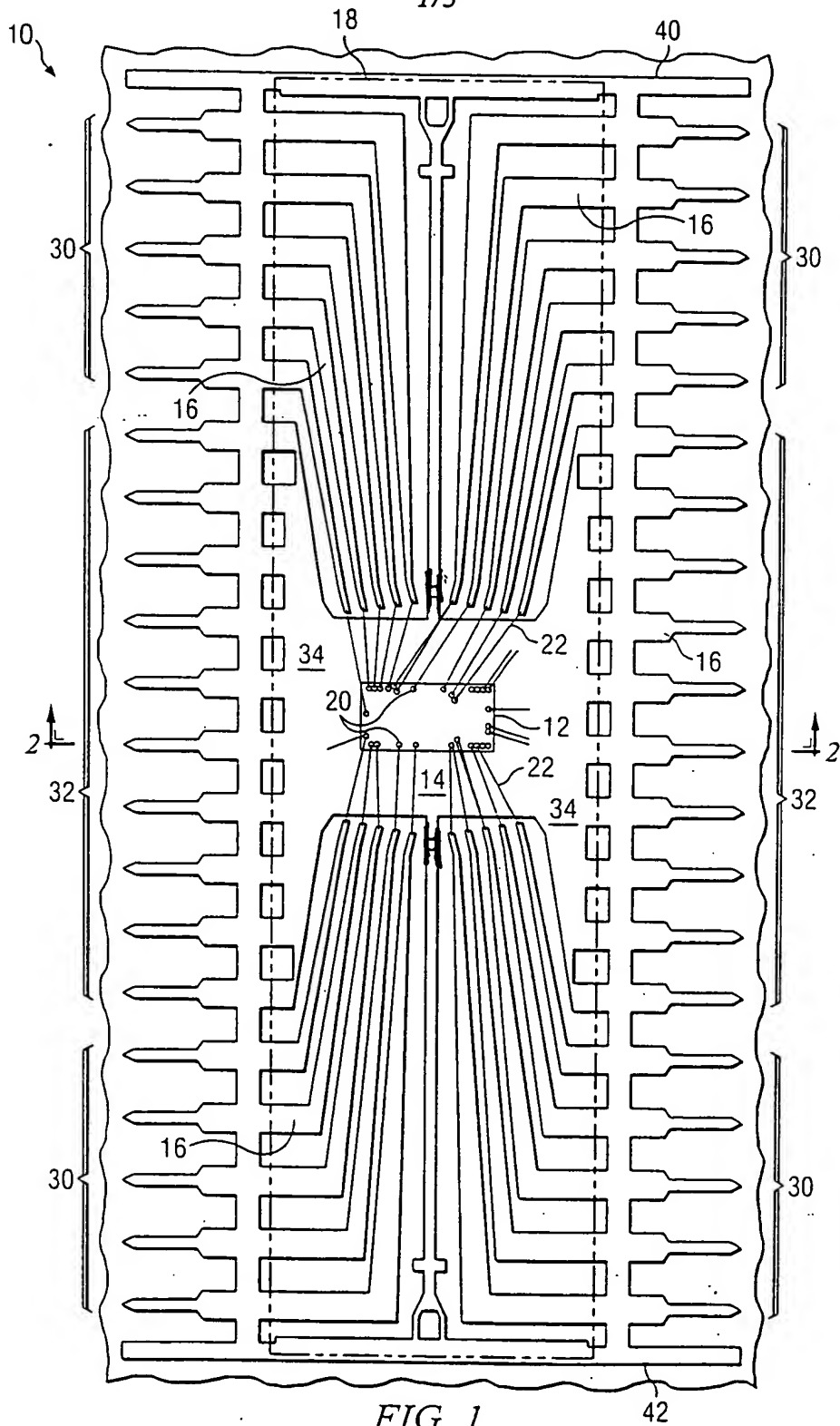
10/723,036

Attorney Docket No.: TI-36847
~~032350 P. 10~~
~~Plastic Dual In-Line Packaging (PDIP)~~
~~Having Enhanced Heat Dissipation~~
~~By: Anthony L. Coyle~~

Annotated
Sheet

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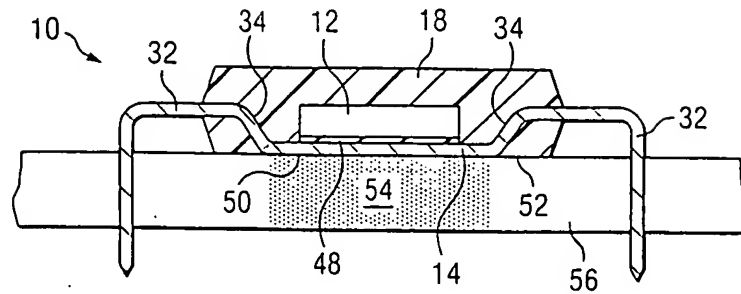


FIG. 2

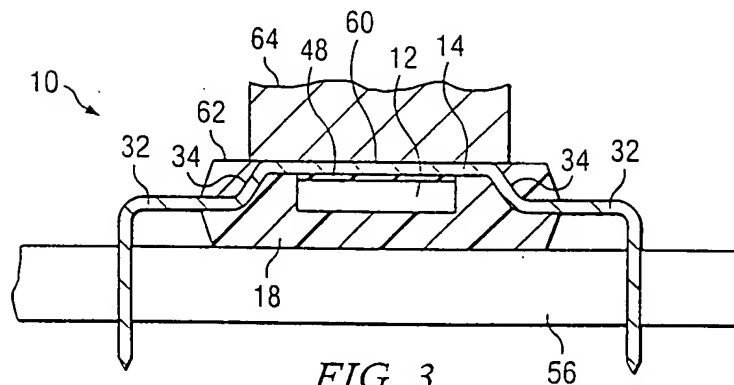


FIG. 3

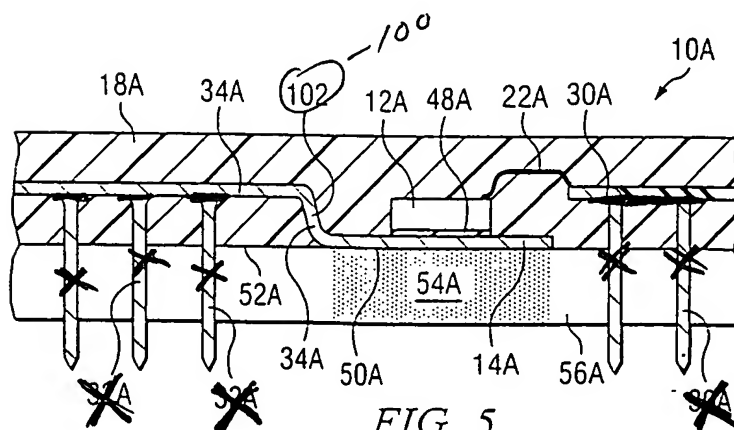


FIG. 5

10/723 036

Patent Docket No.: T1-3604/
(032350.B470)
~~Plastic Dual-In-Line Packaging (PDIP)~~
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Annotated
Sheet

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10A

